

### Surface mount high linearity wideband silicon NPN RF bipolar transistor



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## **Product description**

The BFP450 is a low noise device based on a grounded emitter (SIEGET<sup>™</sup>) that is part of Infineon's established fourth generation RF bipolar transistor family. Its transition frequency  $f_T$  of 24 GHz, collector design and high linearity characteristics make the device suitable for energy efficiency applications up to 3 GHz. It remains cost competitive without compromising on ease of use.



### **Feature list**

- Minimum noise figure  $NF_{min}$  = 1.7 dB at 1.9 GHz, 3 V, 50 mA
- High gain  $G_{ma}$  = 15.5 dB at 1.9 GHz, 3 V, 90 mA
- *OIP*<sub>3</sub> = 31 dBm at 1.9 GHz, 3 V, 90 mA

### **Product validation**

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

## **Potential applications**

- **Broadband amplifiers**
- Low noise, high linearity amplifiers for sub-1 GHz ISM band applications

### **Device information**

#### **Part information** Table 1

Product name / Ordering code	Package	Pin co	nfigura	tion		Marking	Pieces / Reel
BFP450 / BFP450H6327XTSA1	SOT343	1 = B	2 = E	3 = C	4 = E	ANs	3000
BFP450 / BFP450H6433XTMA1							10000

Attention: ESD (Electrostatic discharge) sensitive device, observe handling precautions

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**Absolute maximum ratings** 

#### **Absolute maximum ratings** 1

Table 2 Absolute maximum ratings at  $T_A = 25$  °C (unless otherwise specified)

Parameter	Symbol	Va	lues	Unit	Note or test condition
		Min.	Max.		
Collector emitter voltage	V <sub>CEO</sub>	_	4.5	٧	Open base
			4.1		T <sub>A</sub> = -55 °C, open base
Collector emitter voltage	V <sub>CES</sub>		15		E-B short circuited
Collector base voltage	V <sub>CBO</sub>		15		Open emitter
Emitter base voltage	V <sub>EBO</sub>		1.5		Open collector
Base current	I <sub>B</sub>		10	mA	-
Collector current	I <sub>C</sub>		170		
Total power dissipation 1)	P <sub>tot</sub>		500	mW	<i>T</i> <sub>S</sub> ≤ 90 °C
Junction temperature	TJ	1	150	°C	-
Storage temperature	$T_{Stg}$	-55			

Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding only one of these values may cause irreversible damage to the integrated circuit.

 $T_S$  is the soldering point temperature.  $T_S$  is measured on the emitter lead at the soldering point of the PCB.



Thermal characteristics

## 2 Thermal characteristics

Table 3 Thermal resistance

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Junction - soldering point	R <sub>thJS</sub>	_	120	_	K/W	-

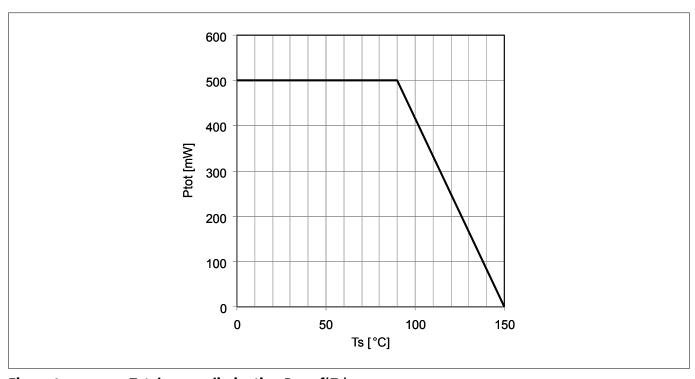


Figure 1 Total power dissipation  $P_{\text{tot}} = f(T_S)$ 

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#### **Electrical characteristics**

### 3 Electrical characteristics

#### 3.1 DC characteristics

Table 4 DC characteristics at  $T_A = 25$  °C

Parameter	Symbol		Values	i	Unit	Note or test condition	
		Min.	Тур.	Max.			
Collector emitter breakdown voltage	V <sub>(BR)CEO</sub>	4.5	5	-	V	$I_C = 1 \text{ mA}, I_B = 0,$ open base	
Collector emitter leakage current	I <sub>CES</sub>	_	1	1 <sup>2)</sup> 30 <sup>2)</sup>	μA nA	$V_{CE} = 15 \text{ V}, V_{BE} = 0,$ $V_{CE} = 3 \text{ V}, V_{BE} = 0,$ E-B short circuited	
Collector base leakage current	I <sub>CBO</sub>		1	30 <sup>2)</sup>	nA	$V_{\text{CB}} = 3 \text{ V}, I_{\text{E}} = 0,$ open emitter	
Emitter base leakage current	I <sub>EBO</sub>		0.05	3 <sup>2)</sup>	μΑ	$V_{\rm EB} = 0.5 \text{V}, I_{\rm C} = 0,$ open collector	
DC current gain	h <sub>FE</sub>	60 50	95 85	130 120		$V_{CE} = 4 \text{ V}, I_C = 50 \text{ mA},$ $V_{CE} = 3 \text{ V}, I_C = 90 \text{ mA},$ pulse measured	

#### 3.2 General AC characteristics

Table 5 General AC characteristics at  $T_A = 25 \,^{\circ}\text{C}$ 

Parameter	Symbol		Values	;	Unit	Note or test condition
		Min.	Тур.	Max.		
Transition frequency	$f_{T}$	18	24	_	GHz	$V_{CE} = 3 \text{ V}, I_{C} = 90 \text{ mA},$ f = 1  GHz
Collector base capacitance	ССВ	_	0.48	0.8	pF	$V_{CB} = 3 \text{ V}, V_{BE} = 0,$ f = 1  MHz, emitter grounded
Collector emitter capacitance	C <sub>CE</sub>		1.2	-		$V_{CE} = 3 \text{ V}, V_{BE} = 0,$ f = 1  MHz, base grounded
Emitter base capacitance	C <sub>EB</sub>		1.7			$V_{\text{EB}} = 0.5 \text{ V}, V_{\text{CB}} = 0,$ f = 1  MHz, collector grounded

<sup>&</sup>lt;sup>2</sup> Maximum values not limited by the device but by the short cycle time of the 100% test.



## **3.3** Frequency dependent AC characteristics

Measurement setup is a test fixture with Bias-T's in a 50  $\Omega$  system,  $T_{\rm A}$  = 25 °C.

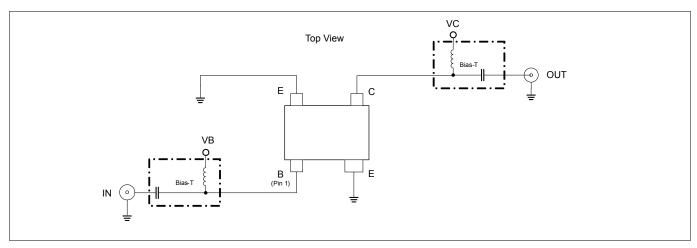


Figure 2 Testing circuit

Table 6 AC characteristics,  $V_{CE} = 3 \text{ V}, f = 150 \text{ MHz}$ 

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Power gain		_		_	dB	
<ul> <li>Maximum power gain</li> </ul>	G <sub>ms</sub>		35.5			$I_{\rm C} = 90  {\rm mA}$
Transducer gain	$ S_{21} ^2$		33.5			
Noise figure						
Minimum noise figure	NF <sub>min</sub>		1.55			$I_{\rm C} = 50  {\rm mA}$
Associated gain	G <sub>ass</sub>		32			
Linearity				1	dBm	
• 3rd order intercept point at output	OIP <sub>3</sub>		30.5			$Z_{\rm S} = Z_{\rm L} = 50 \Omega, I_{\rm C} = 90 \text{m/s}$
• 1 dB gain compression point at output	OP <sub>1dB</sub>		19			

Table 7 AC characteristics,  $V_{CE} = 3 \text{ V}, f = 450 \text{ MHz}$ 

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Power gain		_		_	dB	
<ul> <li>Maximum power gain</li> </ul>	G <sub>ms</sub>		29			$I_{\rm C} = 90  {\rm mA}$
Transducer gain	$ S_{21} ^2$		25			
Noise figure						
Minimum noise figure	NF <sub>min</sub>		1.55			$I_{\rm C} = 50  {\rm mA}$
Associated gain	G <sub>ass</sub>		27.5			
Linearity				1	dBm	
3rd order intercept point at output	OIP <sub>3</sub>		30			$Z_{\rm S} = Z_{\rm L} = 50 \Omega, I_{\rm C} = 90 \rm m$
• 1 dB gain compression point at output	OP <sub>1dB</sub>		19			

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## **Electrical characteristics**

Table 8 AC characteristics,  $V_{CE} = 3 \text{ V}, f = 900 \text{ MHz}$ 

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Power gain		_		_	dB	
<ul> <li>Maximum power gain</li> </ul>	G <sub>ms</sub>		23.5			$I_{\rm C}$ = 90 mA
Transducer gain	$ S_{21} ^2$		19			
Noise figure						
<ul> <li>Minimum noise figure</li> </ul>	NF <sub>min</sub>		1.6			$I_{\rm C} = 50  {\rm mA}$
Associated gain	G <sub>ass</sub>		23			
Linearity					dBm	
3rd order intercept point at output	OIP <sub>3</sub>		30.5			$Z_{\rm S} = Z_{\rm L} = 50 \Omega, I_{\rm C} = 90 \text{m/s}$
• 1 dB gain compression point at output	OP <sub>1dB</sub>		19			

### Table 9 AC characteristics, $V_{CE} = 3 \text{ V}, f = 1.5 \text{ GHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Power gain		_		_	dB	
Maximum power gain	G <sub>ma</sub>		18			$I_{\rm C} = 90  {\rm mA}$
Transducer gain	$ S_{21} ^2$		14			
Noise figure						
Minimum noise figure	<i>NF</i> <sub>min</sub>		1.65			$I_{\rm C} = 50  {\rm mA}$
Associated gain	G <sub>ass</sub>		17			
Linearity					dBm	
3rd order intercept point at output	OIP <sub>3</sub>		31			$Z_{\rm S} = Z_{\rm L} = 50 \Omega, I_{\rm C} = 90 \rm mA$
• 1 dB gain compression point at output	OP <sub>1dB</sub>		19			

## Table 10 AC characteristics, $V_{CE} = 3 \text{ V}, f = 1.9 \text{ GHz}$

Parameter	Symbol		Values		Unit	Note or test condition
		Min.	Тур.	Мах.		
Power gain		_		_	dB	
Maximum power gain	G <sub>ma</sub>		15.5			$I_{\rm C} = 90  {\rm mA}$
Transducer gain	$ S_{21} ^2$		11.5			
Noise figure						
Minimum noise figure	NF <sub>min</sub>		1.7			$I_{\rm C} = 50  {\rm mA}$
Associated gain	G <sub>ass</sub>		14			
Linearity					dBm	
3rd order intercept point at output	OIP <sub>3</sub>		31			$Z_{\rm S} = Z_{\rm L} = 50 \Omega, I_{\rm C} = 90 \text{mA}$
• 1 dB gain compression point at output	OP <sub>1dB</sub>		19			

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#### **Electrical characteristics**

Table 11 AC characteristics,  $V_{CE} = 3 \text{ V}$ , f = 2.4 GHz

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Power gain		_		_	dB	
<ul> <li>Maximum power gain</li> </ul>	G <sub>ma</sub>		13.5			$I_{\rm C} = 90  {\rm mA}$
Transducer gain	$ S_{21} ^2$		9.5			
Noise figure						
Minimum noise figure	NF <sub>min</sub>		1.8			$I_{\rm C} = 50  {\rm mA}$
Associated gain	G <sub>ass</sub>		12			
Linearity					dBm	
• 3rd order intercept point at output	OIP <sub>3</sub>		30			$Z_{\rm S} = Z_{\rm L} = 50 \Omega, I_{\rm C} = 90 \rm m$
• 1 dB gain compression point at output	OP <sub>1dB</sub>		19			

AC characteristics,  $V_{CE} = 3 \text{ V}$ , f = 3.5 GHzTable 12

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Power gain		_		_	dB	
<ul> <li>Maximum power gain</li> </ul>	G <sub>ma</sub>		10			$I_{\rm C} = 90  {\rm mA}$
Transducer gain	$ S_{21} ^2$		6			
Noise figure						
<ul> <li>Minimum noise figure</li> </ul>	<i>NF</i> <sub>min</sub>		2.05			$I_{\rm C} = 50  {\rm mA}$
Associated gain	G <sub>ass</sub>		9			
Linearity					dBm	
3rd order intercept point at output	OIP <sub>3</sub>		29.5			$Z_{\rm S} = Z_{\rm L} = 50 \Omega, I_{\rm C} = 90 \text{m/s}$
• 1 dB gain compression point at output	OP <sub>1dB</sub>		18.5			

Note:

 $G_{\rm ms}$  =  $IS_{21}/S_{12}I$  for k<1;  $G_{\rm ma}$  =  $IS_{21}/S_{12}I$  (k-( $k^2$ -1) $^{1/2}$ ) for k>1. In order to get the NF<sub>min</sub> values stated in this chapter, the test fixture losses have been subtracted from all measured results.  $OIP_3$  value depends on termination of all intermodulation frequency components. Termination used for this measurement is 50  $\Omega$  from 0.1 MHz to 6 GHz.



### 3.4 Characteristic DC diagrams

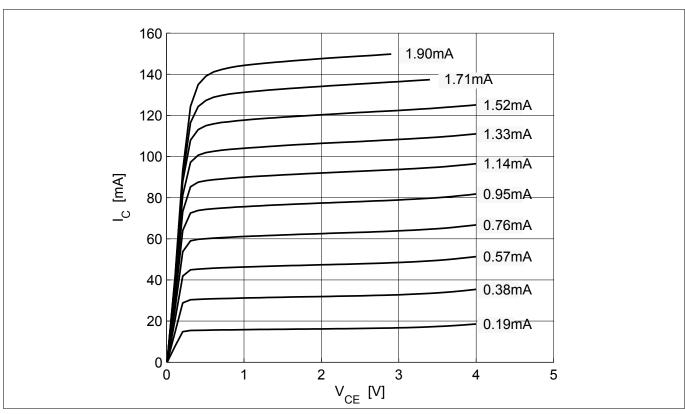


Figure 3 Collector current vs. collector emitter voltage  $I_C = f(V_{CE})$ ,  $I_B = parameter$ 

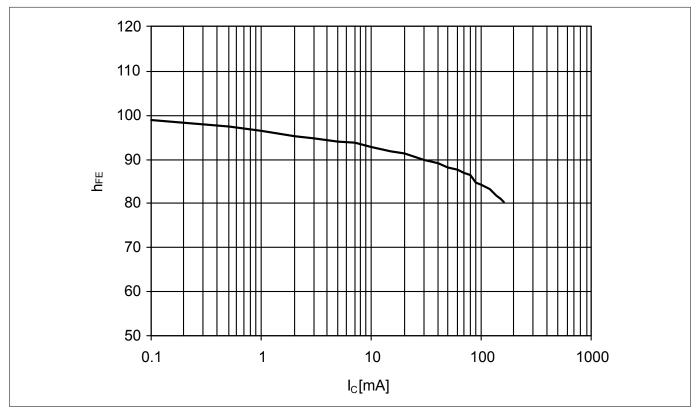


Figure 4 DC current gain  $h_{FE} = f(I_C)$ ,  $V_{CE} = 3 \text{ V}$ 



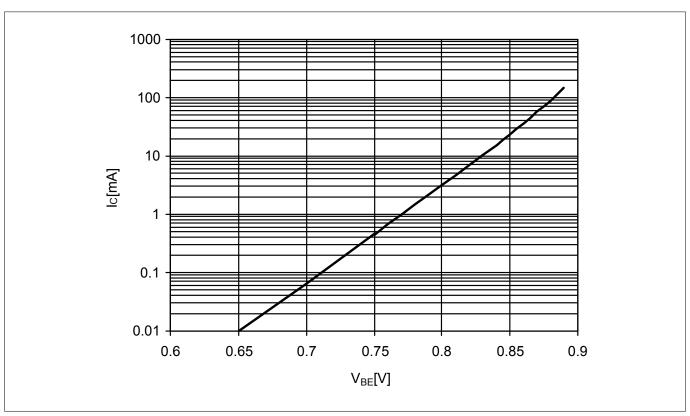


Figure 5 Collector current vs. base emitter forward voltage  $I_C = f(V_{BE})$ ,  $V_{CE} = 2 \text{ V}$ 

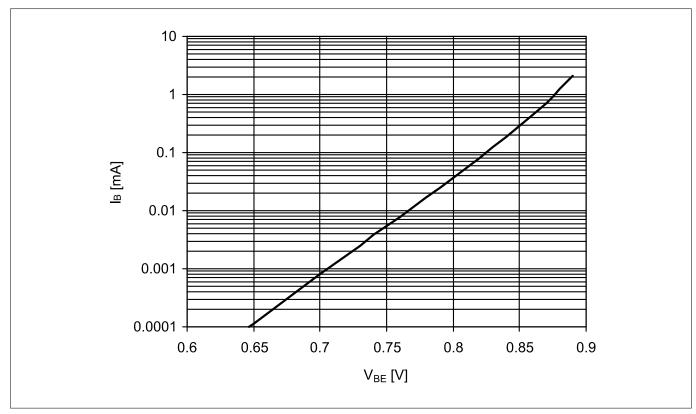


Figure 6 Base current vs. base emitter forward voltage  $I_B = f(V_{BE})$ ,  $V_{CE} = 2 \text{ V}$ 

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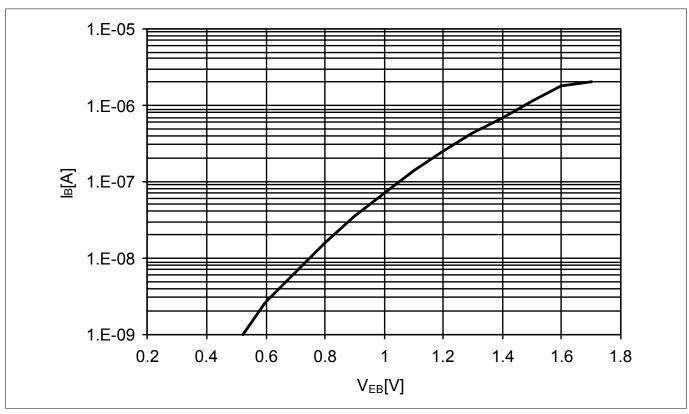


Figure 7 Base current vs. base emitter reverse voltage  $I_B = f(V_{EB})$ ,  $V_{CE} = 2 \text{ V}$ 



### 3.5 Characteristic AC diagrams

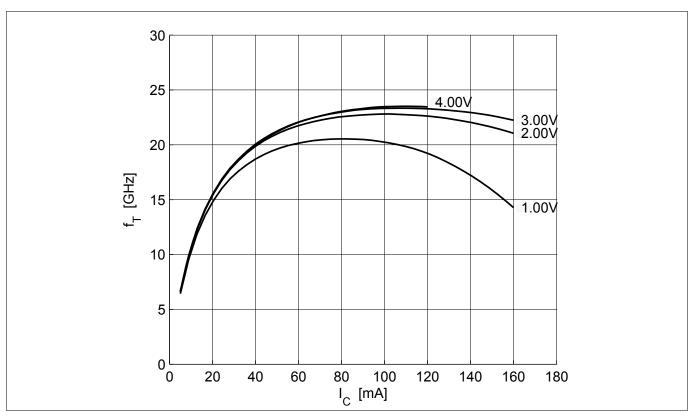


Figure 8 Transition frequency  $f_T = f(I_C)$ , f = 1 GHz,  $V_{CE} =$  parameter

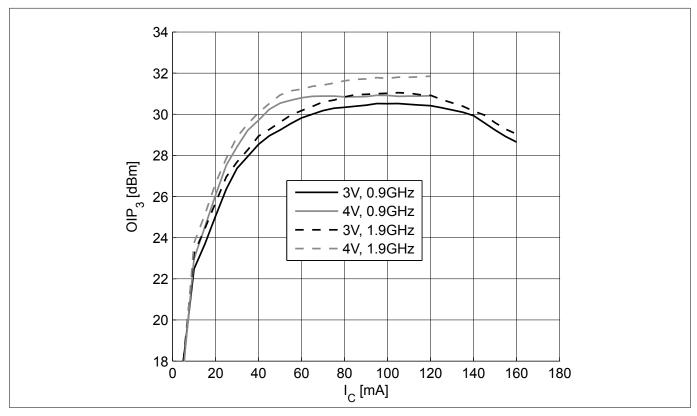


Figure 9 3rd order intercept point  $OIP_3 = f(I_C)$ ,  $Z_S = Z_L = 50 \Omega$ ,  $V_{CE}$ , f = parameters



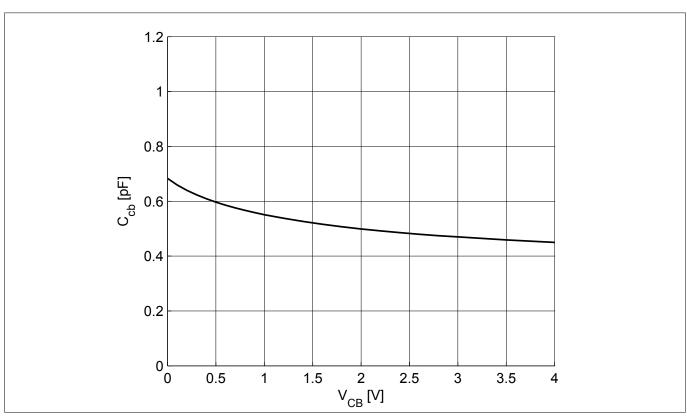


Figure 10 Collector base capacitance  $C_{CB} = f(V_{CB}), f = 1 \text{ MHz}$ 

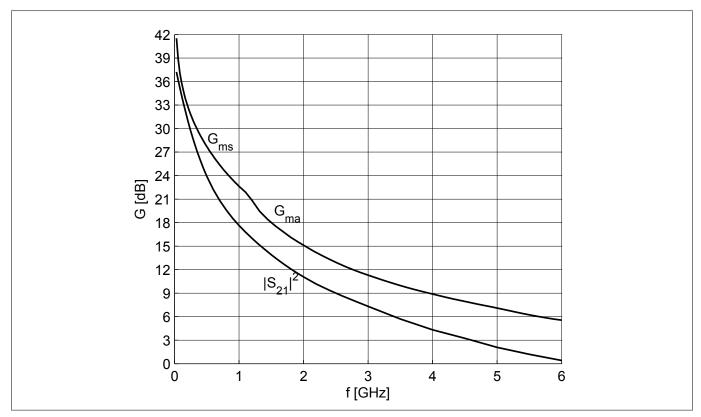


Figure 11 Gain  $G_{ma}$ ,  $G_{ms}$ ,  $IS_{21}I^2 = f(f)$ ,  $V_{CE} = 3 \text{ V}$ ,  $I_C = 90 \text{ mA}$ 

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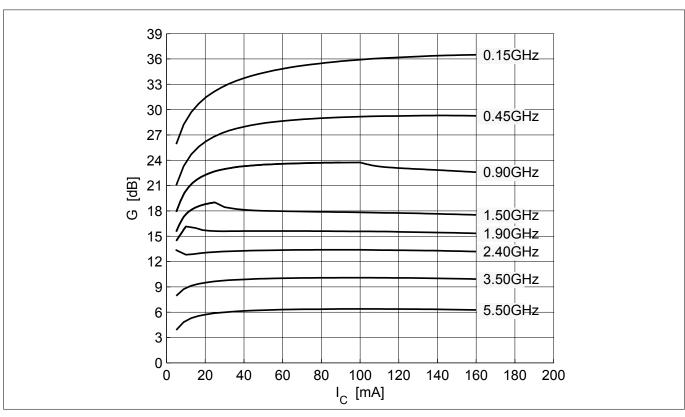


Figure 12 Maximum power gain  $G_{\text{max}} = f(I_{\text{C}})$ ,  $V_{\text{CE}} = 3 \text{ V}$ , f = parameter in GHz

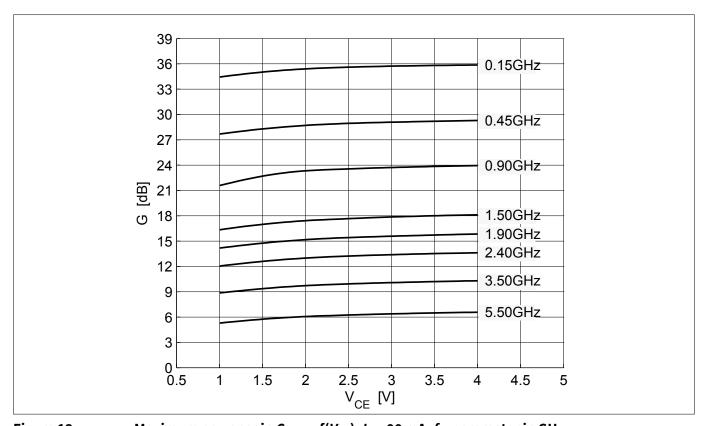
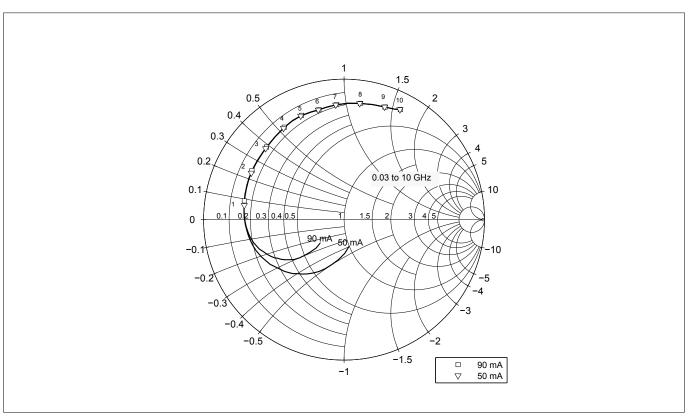
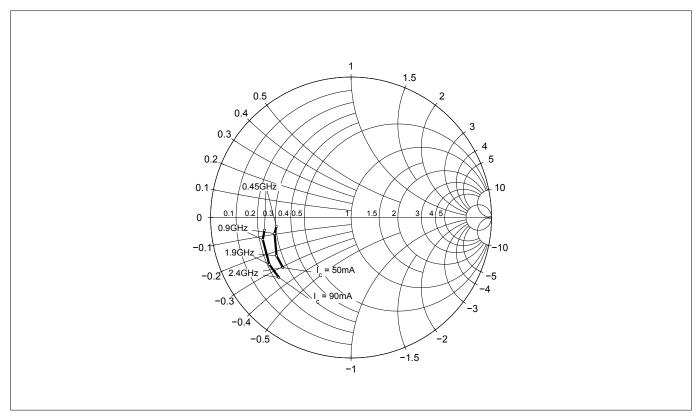


Figure 13 Maximum power gain  $G_{\text{max}} = f(V_{\text{CE}})$ ,  $I_{\text{C}} = 90 \text{ mA}$ , f = parameter in GHz





Input reflection coefficient  $S_{11} = f(f)$ ,  $V_{CE} = 3 \text{ V}$ ,  $I_C = 50 \text{ / } 90 \text{ mA}$ Figure 14



Source impedance for minimum noise figure  $Z_{S,opt} = f(f)$ ,  $V_{CE} = 3 \text{ V}$ ,  $I_C = 50 \text{ / } 90 \text{ mA}$ Figure 15



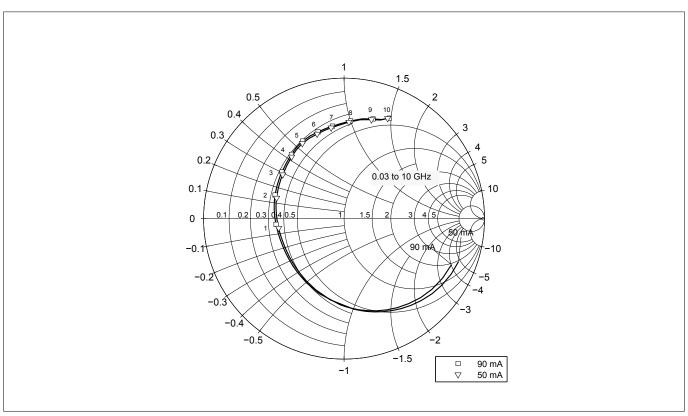


Figure 16 Output reflection coefficient  $S_{22} = f(f)$ ,  $V_{CE} = 3 \text{ V}$ ,  $I_C = 50 / 90 \text{ mA}$ 

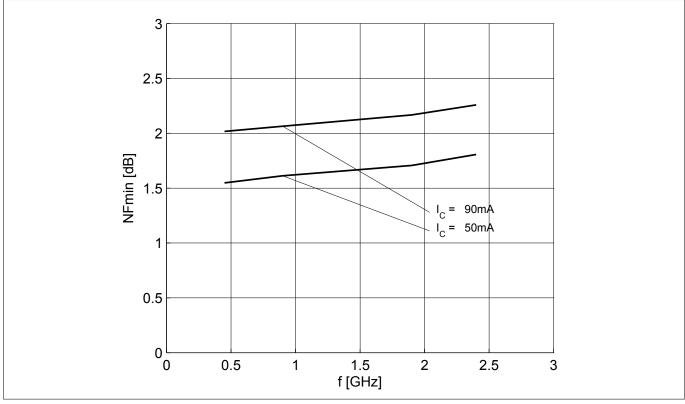


Figure 17 Noise figure  $NF_{min} = f(f)$ ,  $Z_S = Z_{S,opt}$ ,  $V_{CE} = 3 \text{ V}$ ,  $I_C = 50 / 90 \text{ mA}$ 



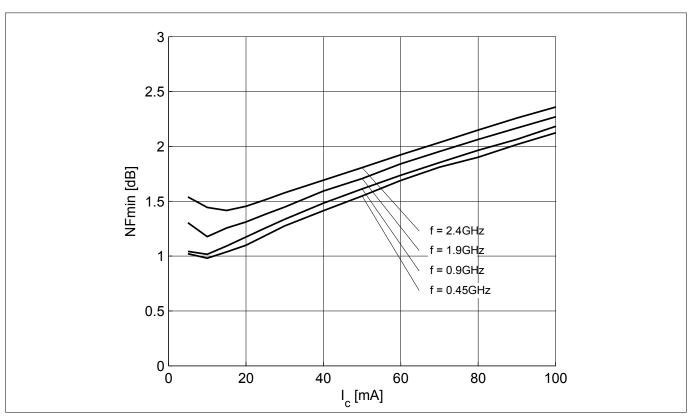


Figure 18 Noise figure  $NF_{min} = f(I_C)$ ,  $Z_S = Z_{S,opt}$ ,  $V_{CE} = 3 \text{ V}$ , f = parameter in GHz

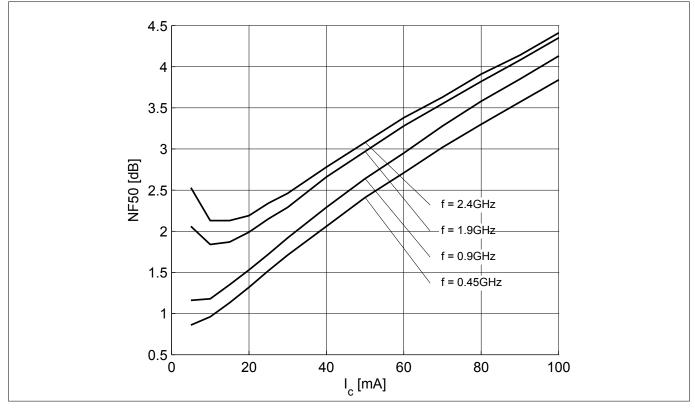


Figure 19 Noise figure  $NF_{50} = f(I_C)$ ,  $Z_S = 50 \Omega$ ,  $V_{CE} = 3 V$ , f = parameter in GHz

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#### **Electrical characteristics**

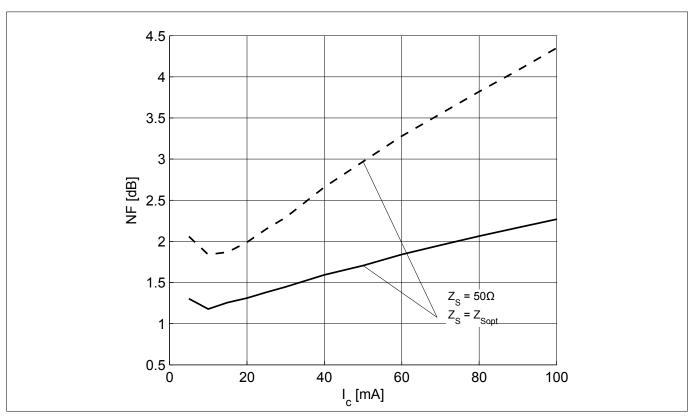


Figure 20 Noise figure  $NF_{50} = f(I_C)$ ,  $Z_S = 50 \Omega$ ,  $NF_{min} = f(I_C)$ ,  $Z_S = Z_{S,opt}$ ,  $V_{CE} = 3 V$ , f = 1.9 GHz

Note: The curves shown in this chapter have been generated using typical devices but shall not be considered as a guarantee that all devices have identical characteristic curves.  $T_A = 25 \,^{\circ}\text{C}$ .



Package information SOT343

## 4 Package information SOT343

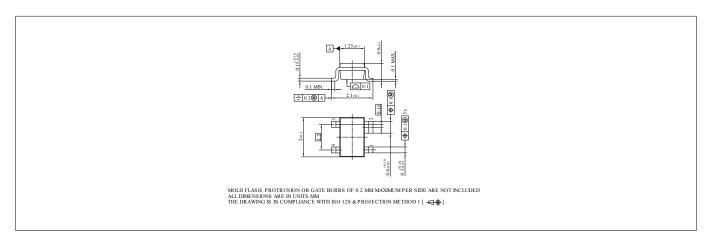


Figure 21 Package outline

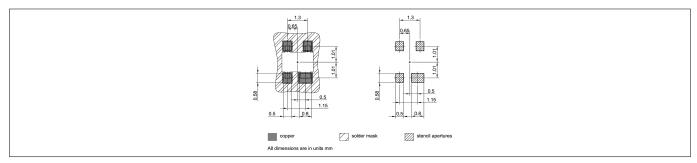


Figure 22 Foot print

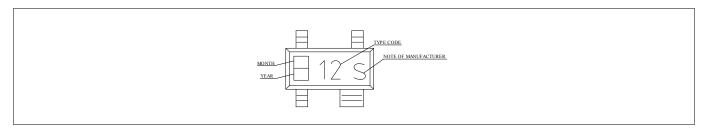


Figure 23 Marking layout example

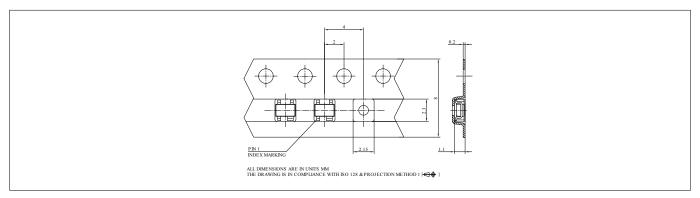


Figure 24 Tape dimensions

### Surface mount high linearity wideband silicon NPN RF bipolar transistor



Revision history

# **Revision history**

Document version	Date of release	Description of changes
Revision 2.0	2019-01-25	New datasheet layout.

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Edition 2019-01-25 Published by Infineon Technologies AG 81726 Munich, Germany

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Document reference IFX-ehy1521536352893

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